Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]
HP 280 G4 SFF Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]“): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain ________ NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>PSU</td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at [EL-MF877-01](#)
### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Hexagon Screw Driver</td>
<td>T-15</td>
</tr>
<tr>
<td>Electric Iron</td>
<td>QUICK 310</td>
</tr>
<tr>
<td>Crisscross Screw Driver</td>
<td>PH1</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove access panel (Step1-2)
2. Disconnect ODD/ HDD power cable and ODD/ HDD SATA cable from ODD (Step3~Step4)
3. Remove ODD/ HDD from chassis (Step4~Step8)
4. Remove all cables and heat sink from MB (Step9~Step12)
5. Separate heatsink(Step13~Step14)
6. Remove the Memory/ CPU/ WLAN/SSD/GFX and Battery from MB (Step14~Step23)
7. Remove MB from chassis (Step24-25)
8. Remove the PSU from chassis (Step26~Step28)
9. Separate PSU and remove the Electrolytic Capacitors (Step 29~Step33)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1: Use T-15 screwdriver to loosen thumb screw and remove access panel.

Step 2: Disconnect ODD power cable and ODD SATA cable from ODD.

Step 3: Press the ODD's latch on ODD cage.

Step 4: Remove the ODD from ODD cage.

Step 5: Remove front bezel from chassis.

Step 6: Disconnect HDD power cable and HDD SATA cable from HDD.
Step 7 Remove the driver cage from Chassis

Step 8 Use T-15 screwdriver to loosen the screws of HDD and remove HDD from HDD cage

Step 9 Disconnect all cables from MB

Step 10 Remove the Fan duct from cooler

Step 11 Disconnect Cooler Fan cable from MB

Step 12 Disconnect Cooler Fan cable from MB
Step 13 Use T-15 screwdriver to loosen the screws and remove the fan

Step 14 Separate the fan from CPU heat sink

Step 15 Remove memory from the MB

Step 16 Rotate the handle and open it up
Step 17: Remove the CPU from the board

Step 18: Open the GFX from Lock

Step 19: Remove the GFX from the board

Step 20: Remove SSD M.2 Card

Step 21: Remove WLAN M.2 Card

Step 22: Remove the Antenna from chasis

HPI instructions for this template are available at EL-MF877-01
Step 23: Remove the battery from the system board

Step 24: Use T-15 screwdriver to loosen the screws of MB from board

Step 25: Remove MB from chassis

Step 26: Use T-15 screwdriver to loosen the screws of PSU

Step 27: Press the PSU’s latch on chassis

Step 28: Remove the PSU from chassis
<table>
<thead>
<tr>
<th>Step29</th>
<th>Remove four screws covered</th>
</tr>
</thead>
<tbody>
<tr>
<td>Step30</td>
<td>Remove the screw and open case</td>
</tr>
<tr>
<td>Step31</td>
<td>Loose screws and remove PCB from case</td>
</tr>
<tr>
<td>Step32</td>
<td>Remove Ele-Cap from PCBA</td>
</tr>
</tbody>
</table>

**33. Step30 Show Ele-Cap on PCBA (C1)**